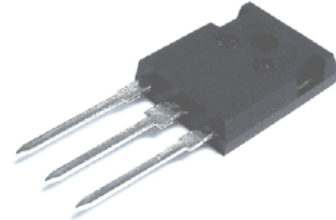
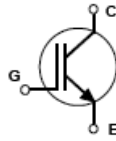


**PRELIMINARY DATASHEET**
**Fast IGBT in NPT technology  
 Series 1200, 8A in TO247 Package**

- Short circuit withstand time - 10 $\mu$ s
- Designed for motor controls, inverters, and SMPS
- High ruggedness, temperature stability
  - Parallel switching capability
- Pb-free lead finish; RoHS compliant


**MAXIMUM RATINGS**

Parameter	Symbol	Value	Units
Collector-emitter voltage	$V_{CE}$	1200	V
DC collector current, limited by $T_{Jmax}$ $T_C = 25^\circ\text{C}$ $T_C = 100^\circ\text{C}$	$I_C$	16.5 7.9	A
Pulsed collector current, $t_p$ limited by $T_{Jmax}$	$I_{Cpulse}$	27	
Turn off safe operating area $V_{CE} \leq 600\text{V}$ , $T_J \leq 150^\circ\text{C}$	-	27	
Gate-emitter voltage	$V_{GE}$	$\pm 20$	V
Avalanche energy, single pulse $I_C = 8\text{A}$ , $V_{CC} = 50\text{V}$ , $R_{GE} = 25\Omega$ , start at $T_J = 25^\circ\text{C}$	$E_{AS}$	40	mJ
Short circuit withstand time <sup>1</sup> $V_{GE} = 15\text{V}$ , $V_{CC} \leq 400\text{V}$ , $T_J \leq 150^\circ\text{C}$	$t_{SC}$	10	$\mu\text{s}$
Power dissipation $T_C = 25^\circ\text{C}$	$P_{tot}$	100	W
Soldering temperature Wave soldering, 1.6 mm (0.063 in.) from case for 10s	$T_S$	260	$^\circ\text{C}$
Operating junction and storage temperature	$T_J, T_{stg}$	-55... +150	$^\circ\text{C}$

**Thermal Resistance**

Parameter	Symbol	Max. Value	Units
<b>Characteristics</b>			
IGBT thermal resistance, junction to case	$R_{thJC}$	1.25	K/W
Thermal resistance, junction to ambient	$R_{thJA}$	62	

<sup>1</sup> Allowed number of short circuits: < 1000; time between short circuits: > 1s.

CAUTION: These devices are ESD sensitive. Use proper handling procedure.

**ELECTRICAL CHARACTERISTICS**, at  $T_j = 25^\circ\text{C}$ , unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
			Min.	Typ.	Max.	
<b>Static Characteristics</b>						
Collector-emitter breakdown voltage	$V_{(BR)CES}$	$V_{GE} = 0V, I_C = 0.5mA$	1200	-	-	V
Collector-emitter saturation voltage	$V_{CE(sat)}$	$V_{GE} = 15V, I_C = 8A$ $T_J = 25^\circ\text{C}$ $T_J = 150^\circ\text{C}$	2.5 -	3.1 3.7	3.6 4.3	
Gate-emitter threshold voltage	$V_{GE(th)}$	$I_C = 0.35mA, V_{CE} = V_{GE}$	3	4	5	
Zero gate voltage collector current	$I_{CES}$	$V_{CE} = 1200V, V_{GE} = 0V$ $T_J = 25^\circ\text{C}$ $T_J = 150^\circ\text{C}$	- -	- -	100 400	$\mu\text{A}$
Gate-emitter leakage current	$I_{GES}$	$V_{CE} = 0V, V_{GE} = 20V$	-	-	100	nA
Transconductance	$g_{fs}$	$V_{CE} = 20V, I_C = 8A$	-	6	-	S
<b>Dynamic Characteristics</b>						
Input capacitance	$C_{iss}$	$V_{CE} = 25V,$ $V_{GE} = 0V,$ $f = 1\text{MHz}$	-	720	870	pF
Output capacitance	$C_{oss}$		-	60	75	
Reverse transfer capacitance	$C_{rss}$		-	40	50	
Gate charge	$Q_G$	$V_{CC} = 960V, I_C = 8A$ $V_{GE} = 15V$	-	70	90	nC
Internal emitter inductance measured 5mm (0.197 in.) from case	$L_E$		-	7	-	nH
Short circuit collector current <sup>1</sup>	$I_{C(SC)}$	$V_{GE} = 15V, t_{sc} \leq 10\mu\text{s}$ $100 \leq V_{CC} \leq 1200V,$ $T_J = 150^\circ\text{C}$	-	75	-	A

**SWITCHING CHARACTERISTICS**

Parameter	Symbol	Conditions	Value			Unit
			Min.	Typ.	Max.	
<b>IGBT Characteristics</b>						
Turn-on delay time	$t_{d(on)}$	$T_j = 25^\circ\text{C},$ $V_{CC} = 800V, I_C = 8A,$ $V_{GE} = 0/15V,$ $R_G = 47\Omega,$ $L_{O2} = 180\text{nH}$ $C_{O2} = 40\text{pF}$	-	27	35	ns
Rise time	$t_r$		-	29	38	
Turn-off delay time	$t_{d(off)}$		-	440	570	
Fall time	$t_f$		-	21	12	
Turn-on energy	$E_{on}$	Energy losses included tail and diode reverse recovery.	-	0.6	0.8	mJ
Turn-off energy	$E_{off}$		-	0.4	0.55	
Total switching energy	$E_{ts}$		-	1.0	1.35	
Turn-on delay time	$t_{d(on)}$	$T_j = 150^\circ\text{C},$ $V_{CC} = 800V, I_C = 8A,$ $V_{GE} = 0/15V,$ $R_G = 47\Omega,$ $L_{O2} = 180\text{nH}$ $C_{O2} = 40\text{pF}$	-	30	36	ns
Rise time	$t_r$		-	26	31	
Turn-off delay time	$t_{d(off)}$		-	490	590	
Fall time	$t_f$		-	30	36	
Turn-on energy	$E_{on}$	Energy losses included tail and diode reverse recovery.	-	1.0	1.2	mJ
Turn-off energy	$E_{off}$		-	0.7	0.9	
Total switching energy	$E_{ts}$		-	1.7	2.1	

**Package Outline Drawing**

